

2SD1577

Silicon NPN Triple-Diffused Junction Mesa Type

Horizontal Deflection Output

■ Features

- High breakdown voltage and high reliability by glass passivation
- High speed switching
- Wide area of safety operation (ASO)
- "Full Pack" package for simplified mounting on a heat sink with one screw

■ Absolute Maximum Ratings (T_c=25°C)

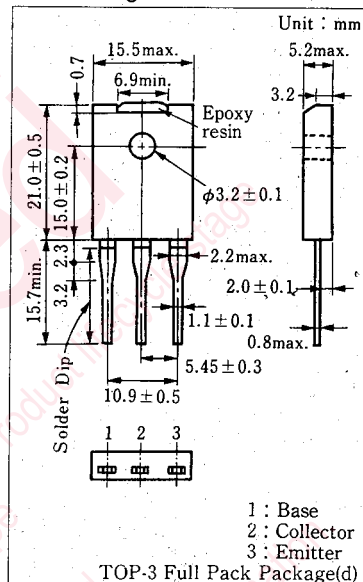
Item	Symbol	Value	Unit
Collector-base voltage	V _{CB0}	1500	V
	V _{CES}	1500	V
Collector-emitter voltage	V _{CEO}	700	V
	V _{EB0}	6	V
Collector current	I _C	5	A
Peak collector current	I _{CP} *	17	A
Peak base current	I _{BP}	3.5	A
Reverse peak base current	I _{BP}	-2.5	A
Collector power dissipation	T _c = 25°C	100	W
	T _a = 25°C	3	
Junction temperature	T _j	150	°C
Storage temperature	T _{stg}	-55 ~ +150	°C

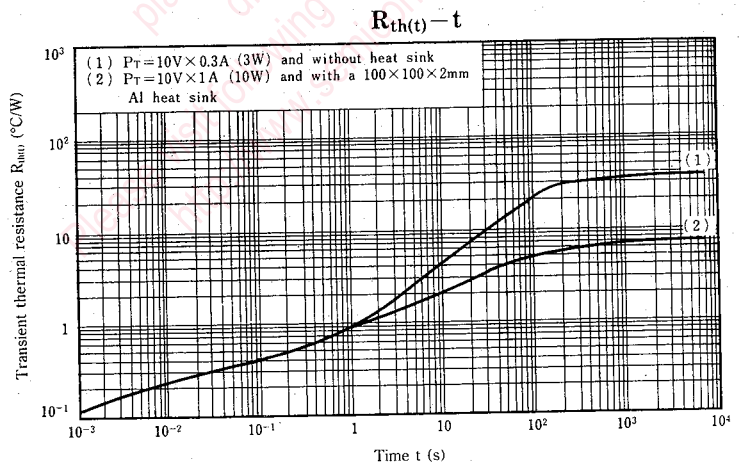
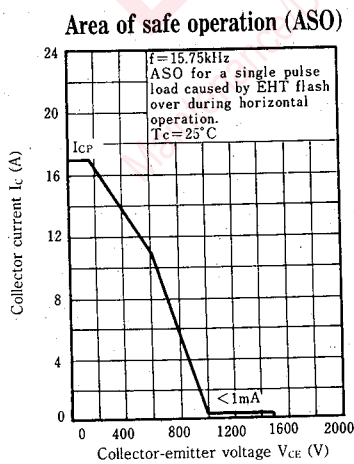
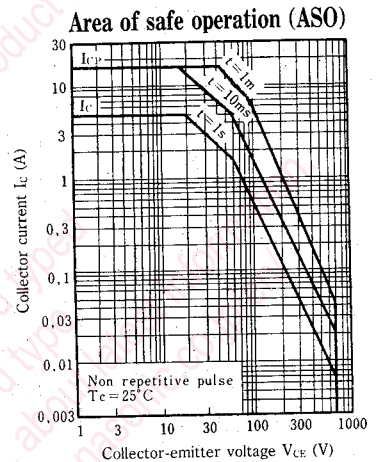
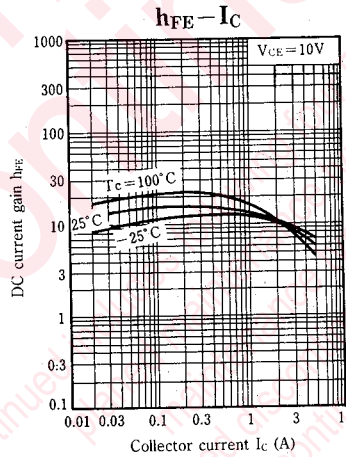
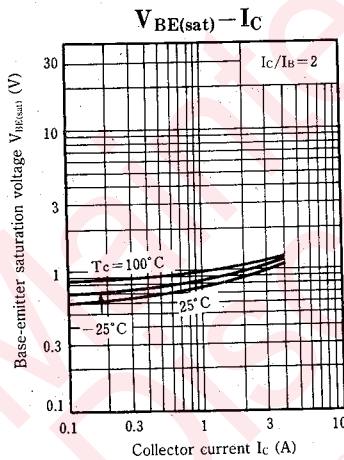
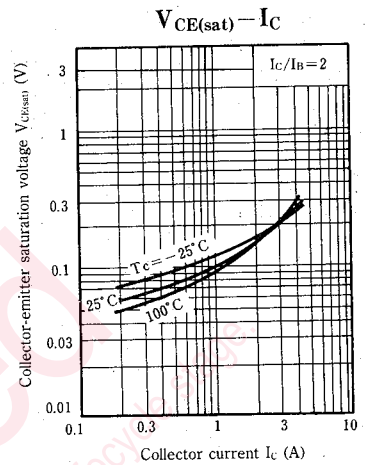
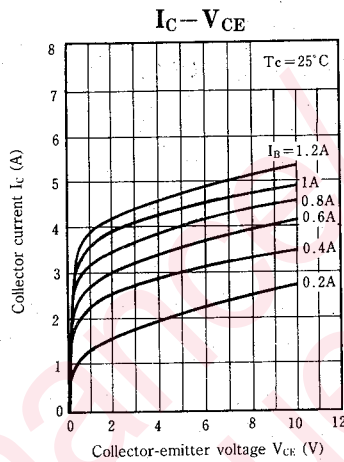
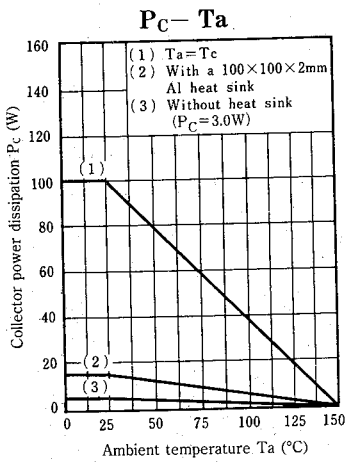
* Non-repetitive peak value

■ Electrical Characteristics (T_c=25°C)

Item	Symbol	Condition	min.	typ.	max.	Unit
Collector cutoff current	I _{CB0}	V _{CB} = 750 V, I _E = 0			50	μA
		V _{CB} = 1500 V, I _E = 0			1	mA
Emitter-base voltage	V _{EB0}	I _E = 1 mA, I _C = 0	6			V
DC current gain	h _{FE}	V _{CE} = 10V, I _C = 4A	4		15	
Collector-emitter saturation voltage	V _{CE(sat)}	I _C = 4.5A, I _B = 2A			2	V
Base-emitter saturation voltage	V _{BE(sat)}	I _C = 4.5A, I _B = 2A			1.3	V
Transition frequency	f _T	V _{CE} = 10V, I _C = 0.5A, f = 0.5MHz		2		MHz
Fall time	t _f	I _C = 4A, I _{Bend} = 1.5A			1	μs
Storage time	t _{stg}	L _B = 10 μH			11	μs

■ Package Dimensions





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